Present: Mack Hall, Jorian Bruslind, and Zach Bendt
Absent: N/A
ECE 342
2/14/19

<div align="center">Week 6 In-Class Group Meeting Notes</div>

- 2nd PCB revision now all components mounted/preliminarily tested
  - Output plugs have been mounted to the PCB
    - Enables full-scale testing with full NEMA-15R inputs and outputs
    - Stress testing components is now the next step
  - Case is still undergoing further revisions
    - Front bottom screw hole will be relocated to align with wall adapter input
    - New revision no longer includes upward cutout for resettable fuse
      - New input plug includes quick-acting fuse within design
        - Old fuse did not act quick enough to be useful anyway
    - New design will now include cutout to support power to user over USB
      - USB power will not be monitored/disableable
    - Screw hole dimensions will be slightly tweaked for easier assembly
  - I^2C voltage and current sensing code is still under development
    - Further debugging has taken place
      - Still inaccurately reading voltage
      - I^2C-experienced Senior has been contacted for potential help
    - Analogue current sensing code is functioning properly
  - App now organizes bluetooth communication packets in a more effective manner
    - Further troubleshooting needed relating to quickly switching relays on/off
      - Sometimes randomly loses connection to MCU
  - WiFi communication framework is under development
    - Utilizes NodeRed servers to update voltage and current values to user
- Group meetings plan to continue every Thursday
  - Communication frequency and quickness in Slack and in-person discussions are satisfactory and should be continued
    - Any additional questions/comments/concerns are highly encouraged to be asked through these channels
- Next steps
  - Try to fix newly introduced app bugs
  - Try to fix I^2C communication between current/voltage sensor and MCU
    - Contacted Scott Merrill about potentially looking over code
  - Introducing/developing WiFi capabilities
  - Stress test mounted components
  - Further revising/printing enclosure